

Application No.: 10772,510

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Reply to Office Action of February 5, 2007

a.) Amendments to Specification

Replace the paragraph [0006] beginning at page 1 in the specification as published with the following rewritten paragraph:

[0006] moving a camera, having an image field field, over a wafer and thereby acquiring with its image field a plurality of images;

Replace the paragraph [0009] beginning at page 1 in the specification as published with the following rewritten paragraph:

[0009] It is an other object of the invention to make available an apparatus for the analysis of surface images of wafers, wherein the apparatus performs comparisons of optical images in an efficient way.

Replace the paragraph [0049] beginning at page 3 in the specification as published with the following rewritten paragraph:

[0049] When the two indices are combined, the first segment receives the index 16 - 1a. The first camera image encompasses image field segments 16 - 1a, 2b, 4c, 5d. The second camera image encompasses image field segments 16 - 3a, 1b, 6c, 4d, etc. The contents of the first and fourth images 16 can be compared with one another, since they match in terms of both SAW index and image index.